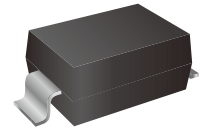


Surface Mount Ultrafast Recovery Rectifier

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case:SMAW
- Terminal:Leads solderable per MIL-STD-750 Method 2026
- Polarity:Color band denotes cathode end
- Mounting Position:Any



Ordering Information

Part Number	Shipping	Reel
LTU1AW THRU LTU1MW	8000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

Parameter	Symbol	LTU1AW	LTU1BW	LTU1DW	LTU1GW	LTU1JW	LTU1KW	LTU1MW	Unit
	Marking	U1AW	U1BW	U1DW	U1GW	U1JW	U1KW	U1MW	
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 110^\circ\text{C}$	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Maximum Instantaneous Forward Voltage at 1 A	V_F	1.0		1.3		1.7			V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Blocking Voltage $T_a = 125^\circ\text{C}$	I_R	5 100							μA
Maximum Reverse Recovery Time (Note1)	T_{RR}	50				75			ns
Typical Thermal Resistance (Note2)	$R_{\theta JA}$	75							$^\circ\text{C/W}$
Typical Junction Capacitance (Note3)	C_J	15							pF
Operating and Storage Temperature Range	T_J, T_{STG}	-55 ~ +150							$^\circ\text{C}$

Note : (1) Measured with $I_F = 0.5\text{ A}$, $I_R = 1\text{ A}$, $I_{rr} = 0.25\text{ A}$.

(2) P.C.B. mounted with 2.0" X 2.0" (5cm X 5cm) copper pad areas.

(3) Measured at 1 MHz and applied reverse voltage of 4 V D.C.



Characteristics Curves

FIG. 1 FORWARD CURRENT DERATING CURVE

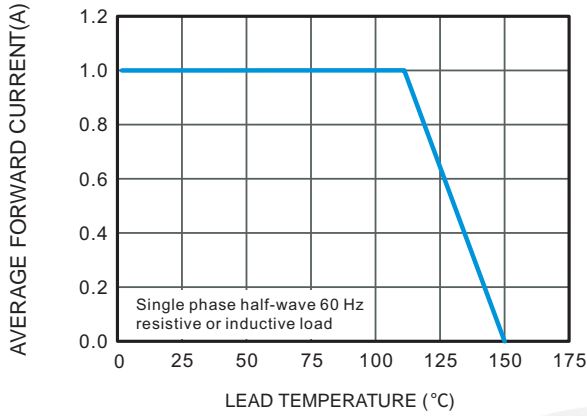


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

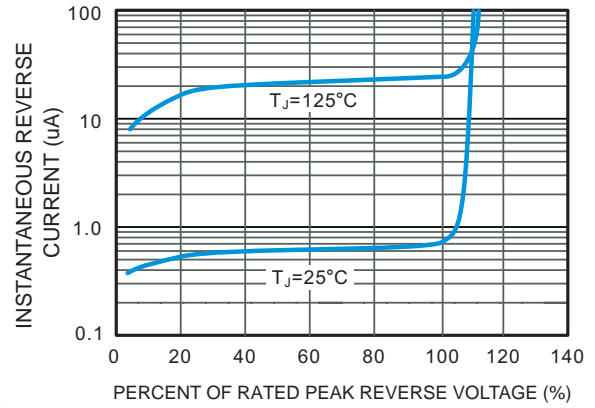


FIG. 3 TYPICAL FORWARD CHARACTERISTICS

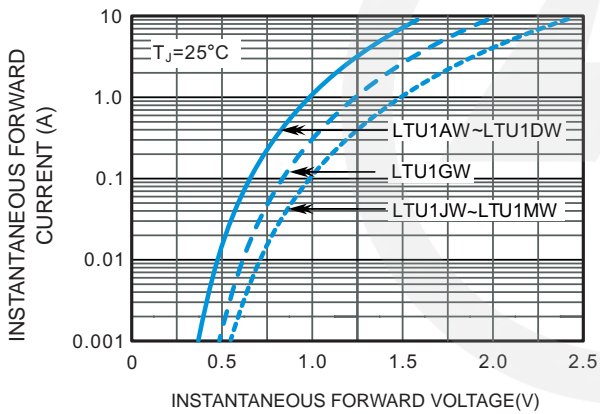


FIG. 4 MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

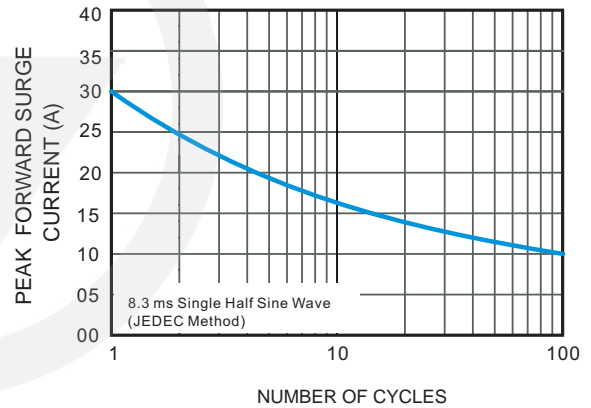


FIG. 5 TYPICAL TRANSIENT THERMAL IMPEDANCE

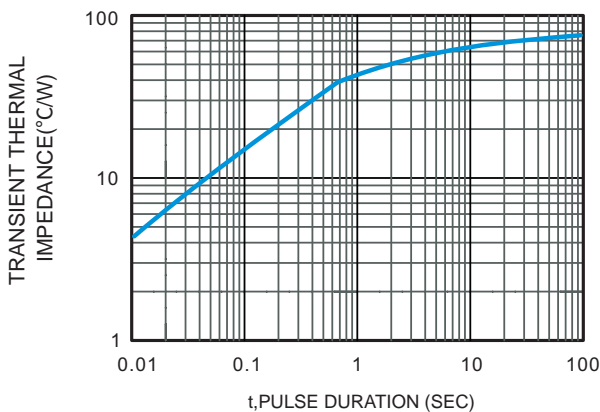
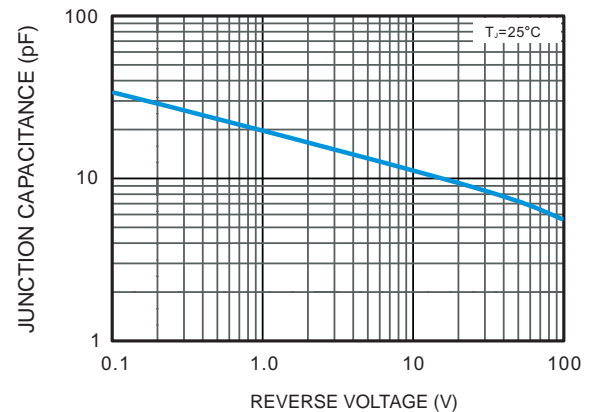
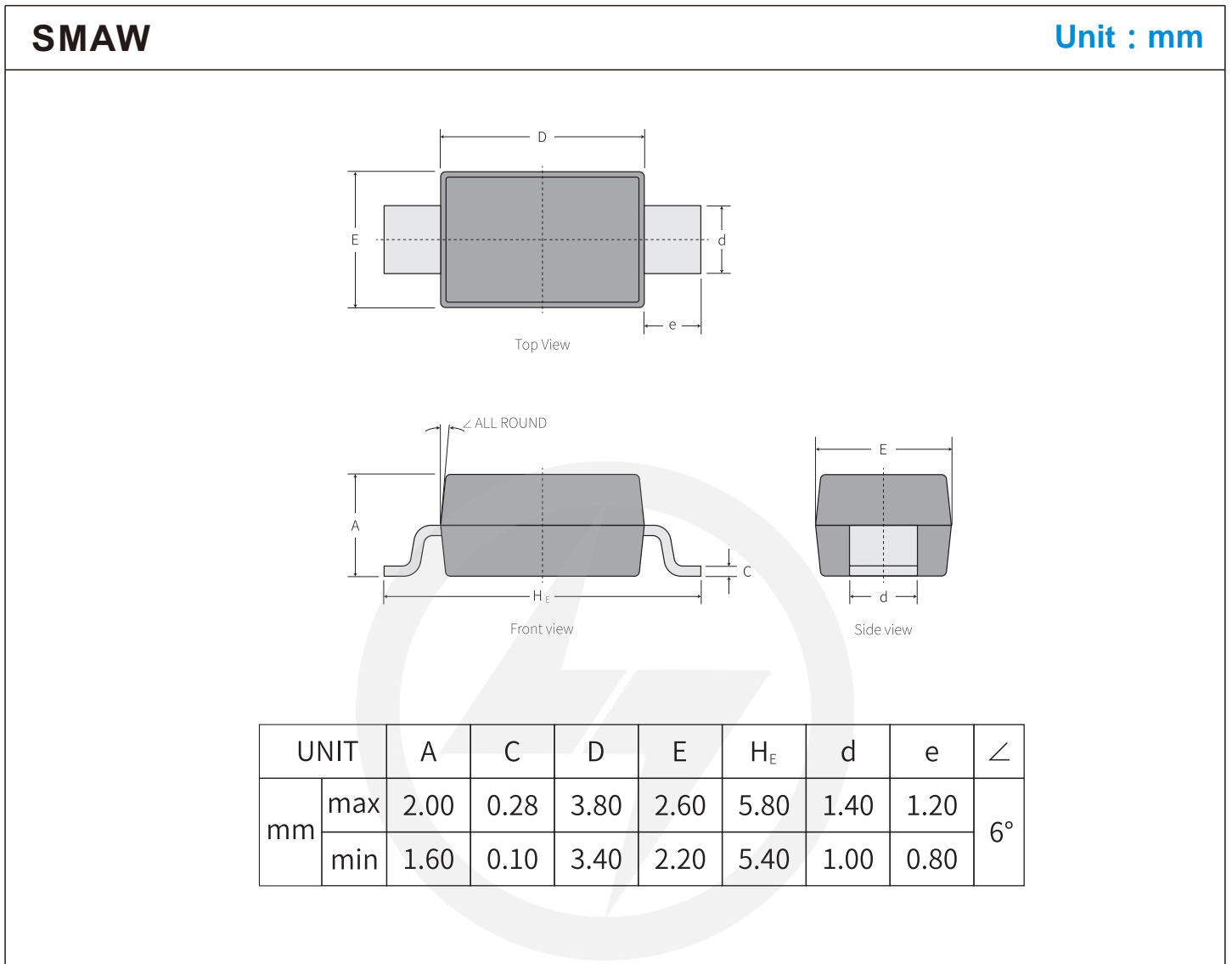


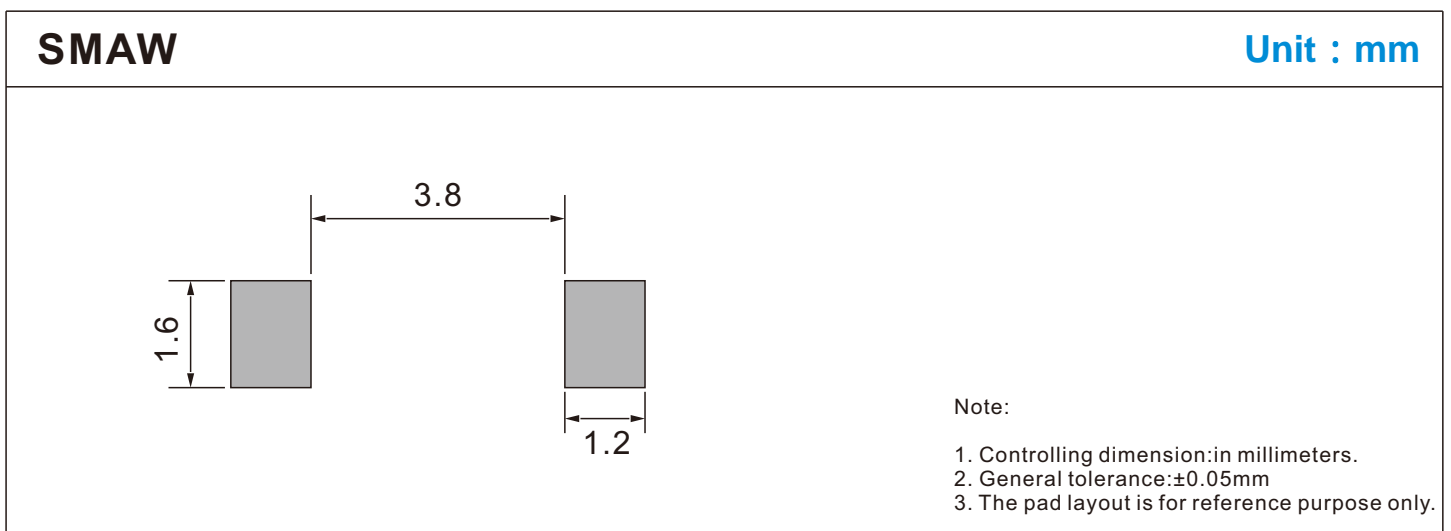
FIG. 6 TYPICAL JUNCTION CAPACITANCE



Package Outline

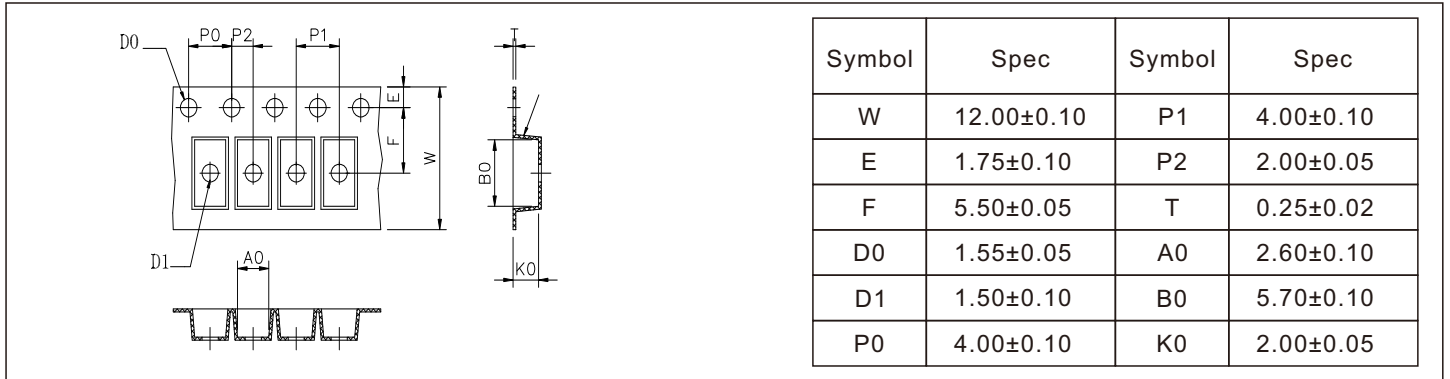


Suggested Pad Layout



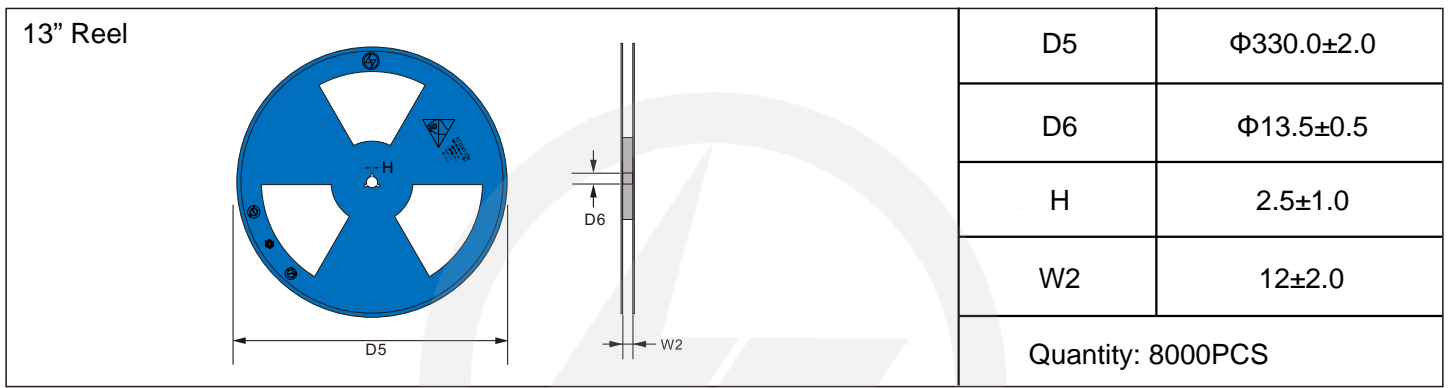
Carrier Tape Dimensions

Unit : mm

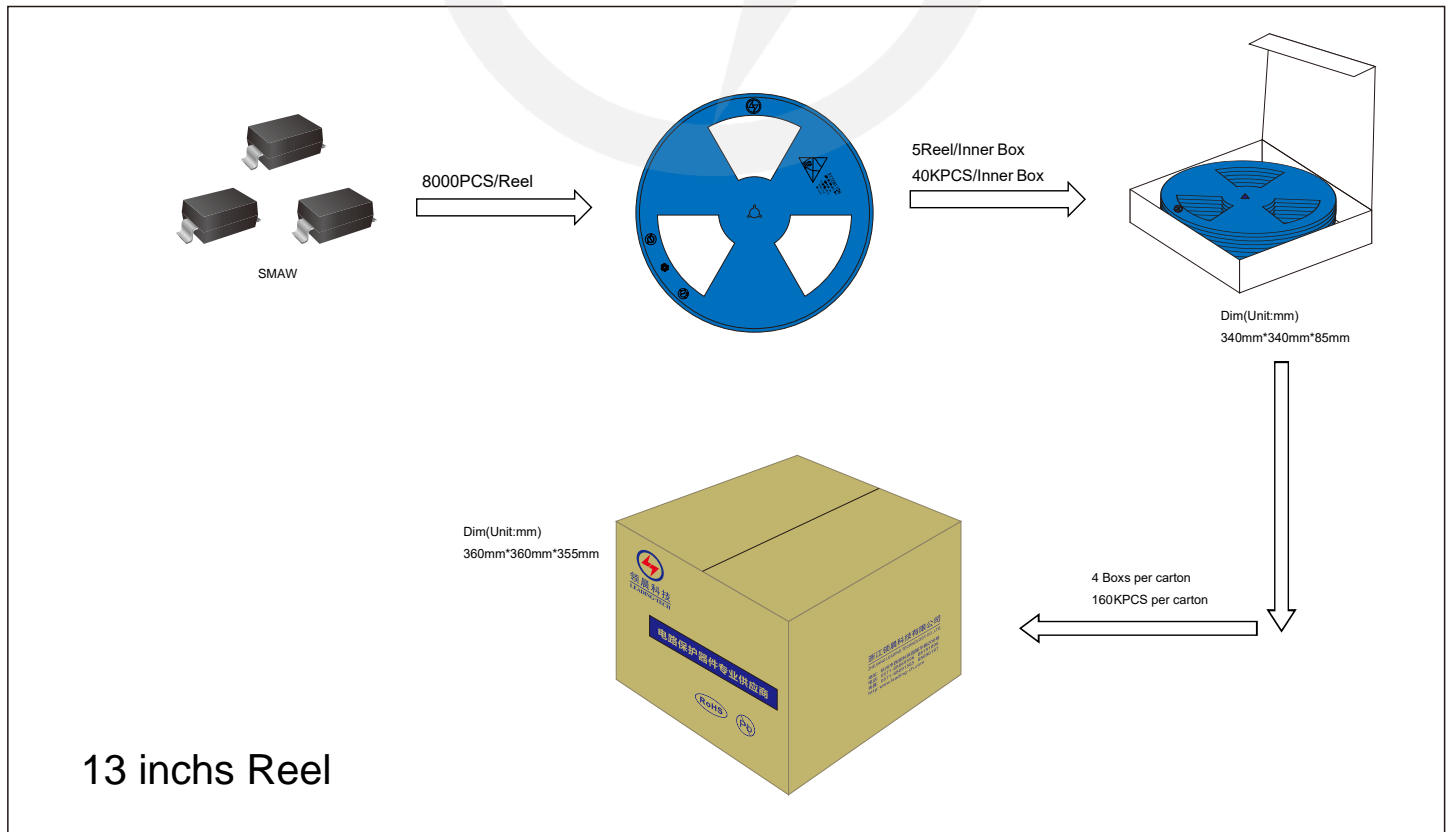


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2023.11.29	2023.11.29	1.0	New File	/	Ding	
02	2025.06.27	2025.06.27	1.1	Update packaging information	/	Ding	